

Solutions and Innovations for TOC and VOC Measurements regarding Cleanliness Grades in the High-Tech and Semiconductor Industry

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Clean Event 2023
Veldhoven

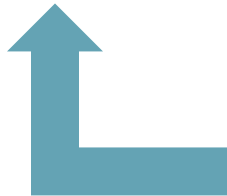


Who am I?

- Expert in GC&MS methods
- Visiting professor UGent
- Lean black belt

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Who is Interscience?

- GC&MS instruments
- Sample preparation
- Hands-on training

www.interscience.nl

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CLEANLINESS TESTING



Assessment of product emission levels

- Routine material emission testing
- Non-routine material emission testing
- Cleanroom air analysis

ROUTINE MATERIAL EMISSION TESTING

GSA 07 9710

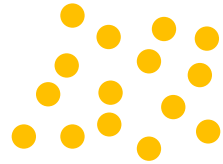


High purity
input gas



'Contaminated'
output gas

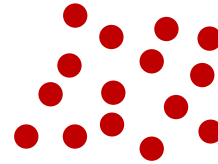
ROUTINE MATERIAL EMISSION TESTING



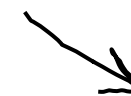
TOC Volatile
 TOC_v



$BP < 150\text{ }^{\circ}\text{C}$
 $MW < 120\text{ g/mol}$



TOC Non-Volatile
 TOC_{nv}



$BP > 150\text{ }^{\circ}\text{C}$
 $MW > 120\text{ g/mol}$

ROUTINE MATERIAL EMISSION TESTING

Preferred technique: TD-GC/FID

- Sampling: Microchamber extraction
- Tube: Tenax/graphitized carbon
- Analysis: Thermal desorption
- Quantification: Toluene in nitrogen (3-point calcurve)
- Reportable parameters: TOC_v and TOC_{nv}

ROUTINE MATERIAL EMISSION TESTING

① Sampling: microchamber

- Standard method (ISO, ASTM)
- Sample placed in small furnace
- Temperature: 25 – 250°C
- Emissions flushed to tube with nitrogen



ROUTINE MATERIAL EMISSION TESTING

② Trapping: adsorbent tube

- Tenax/graphitized carbon
 - Tenax = TOC_{nv}
 - Graphitized carbon = TOC_{v}
- RFID tag for traceability



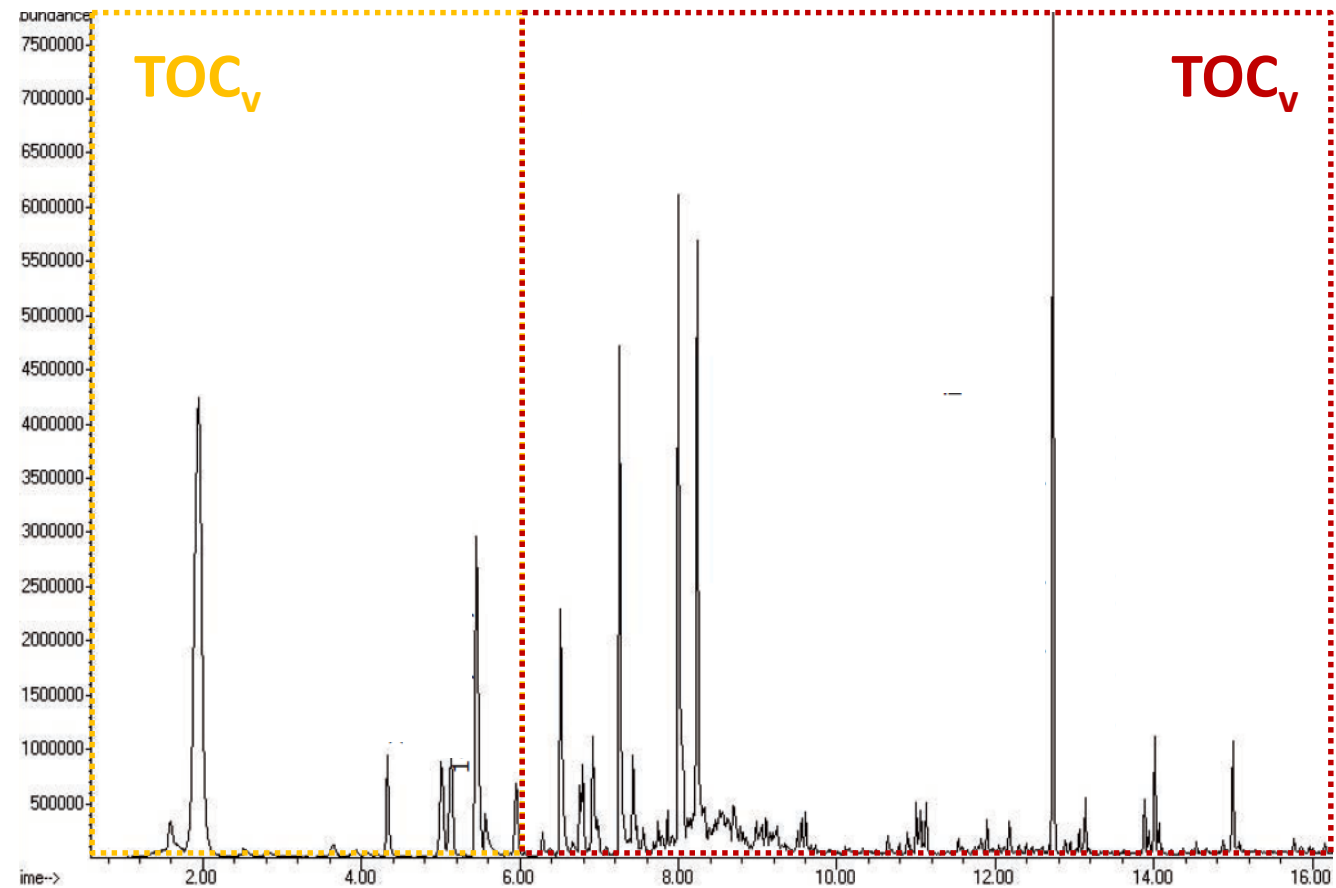
ROUTINE MATERIAL EMISSION TESTING

③ Analysis: thermal desorption

- Reversed flush desorption, 250°C
- Component refocusing, > 0°C
- Flash injection to GC



ROUTINE MATERIAL EMISSION TESTING



NON-ROUTINE MATERIAL EMISSION TESTING

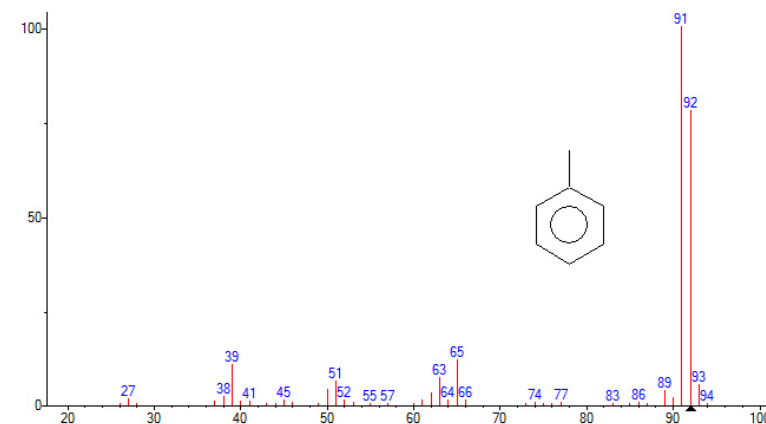
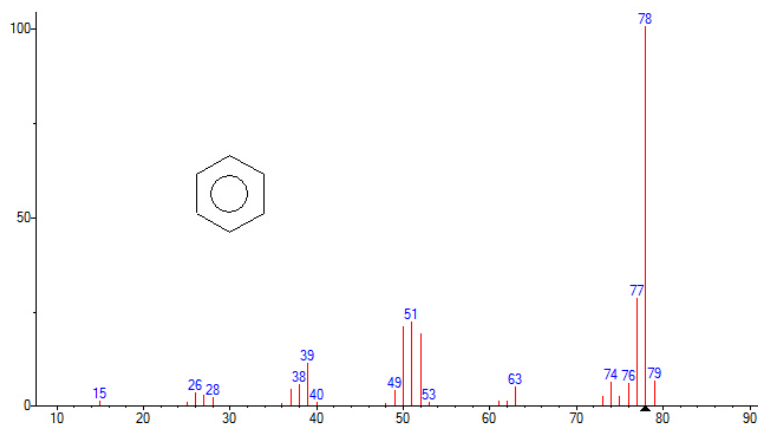
- Identification of unknown components
- Evaluation of new materials
- Troubleshooting QC issues

Preferred technique: TD-GC/MS

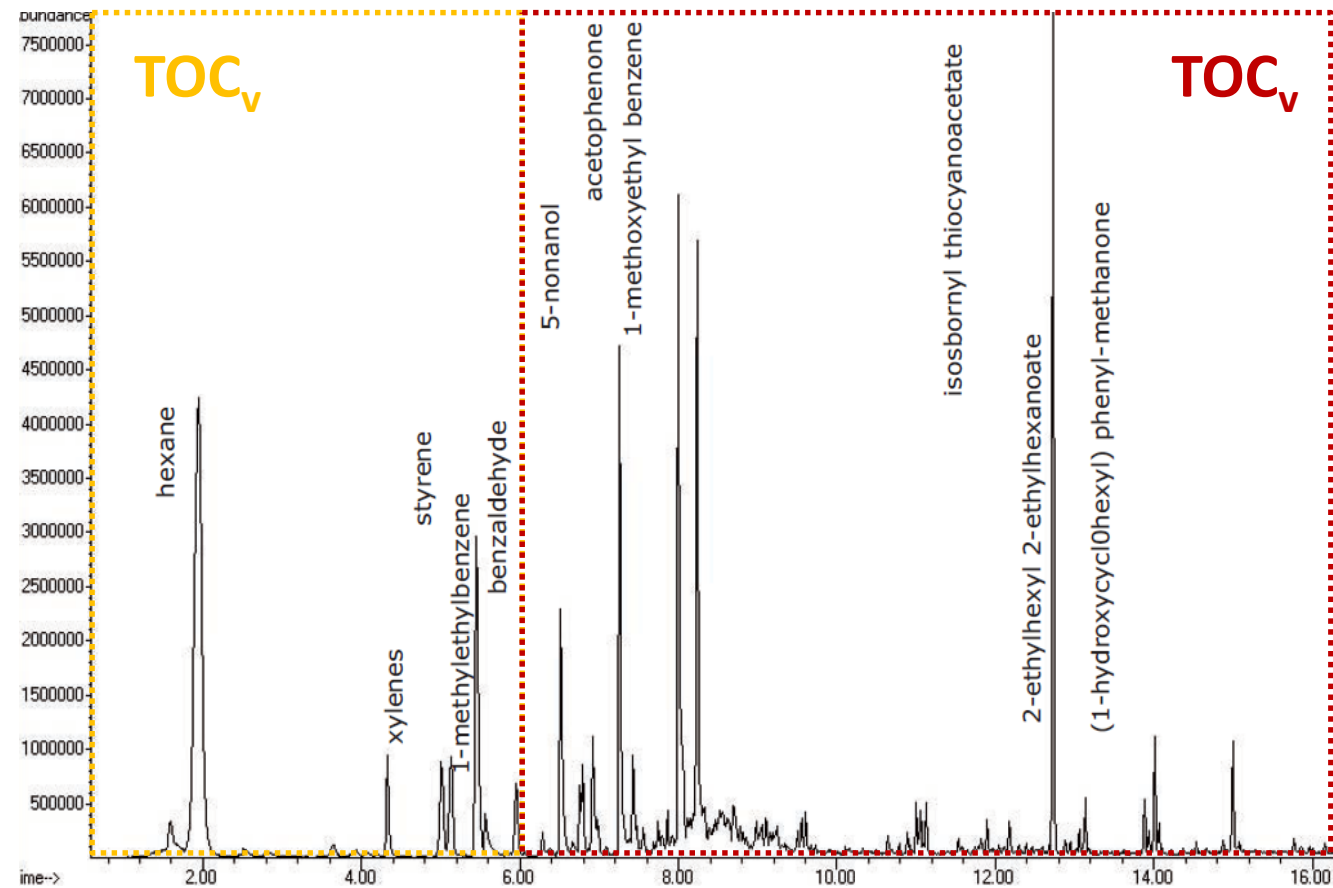
NON-ROUTINE MATERIAL EMISSION TESTING

Why GC/MS?

- Identification of unknown components based on unique MS spectra
- Quantification of known & unknown components based on peak integration
- Full scan/SIM mode for trace and ultratrace analysis in a single run



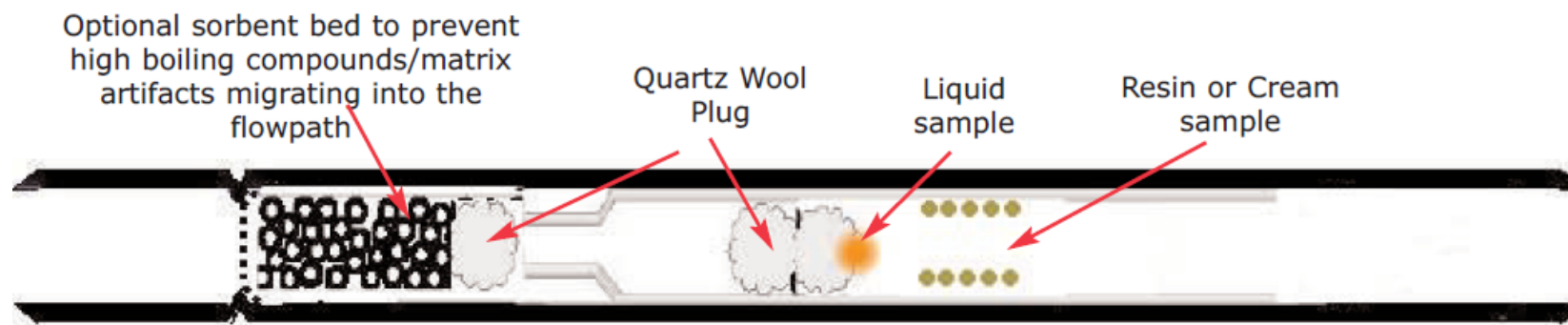
NON-ROUTINE MATERIAL EMISSION TESTING



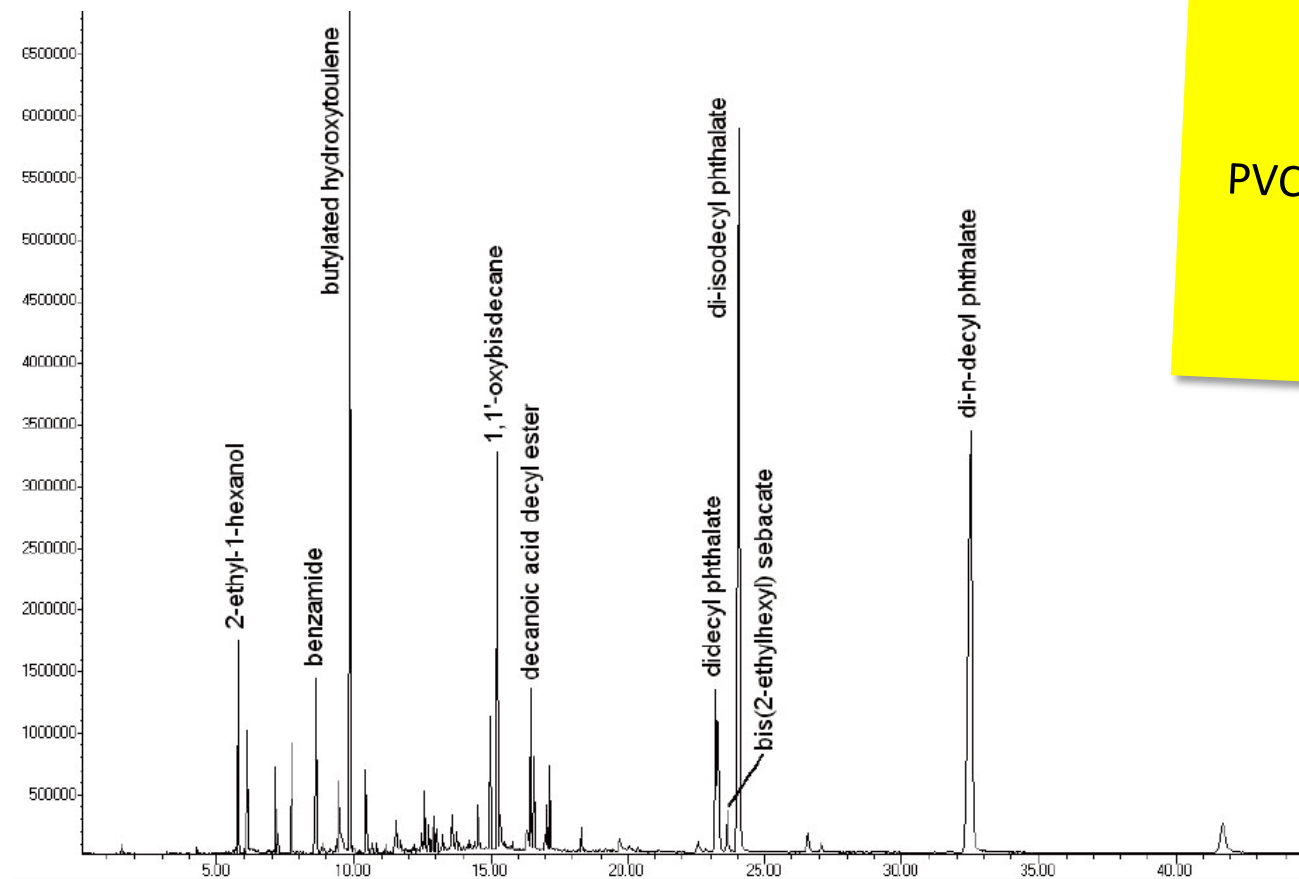
NON-ROUTINE MATERIAL EMISSION TESTING

Direct thermal desorption of materials

- Insert small piece of material in empty tube
- Grind in case of bulk solids
- Use PTFE liner in case of resins/adhesives

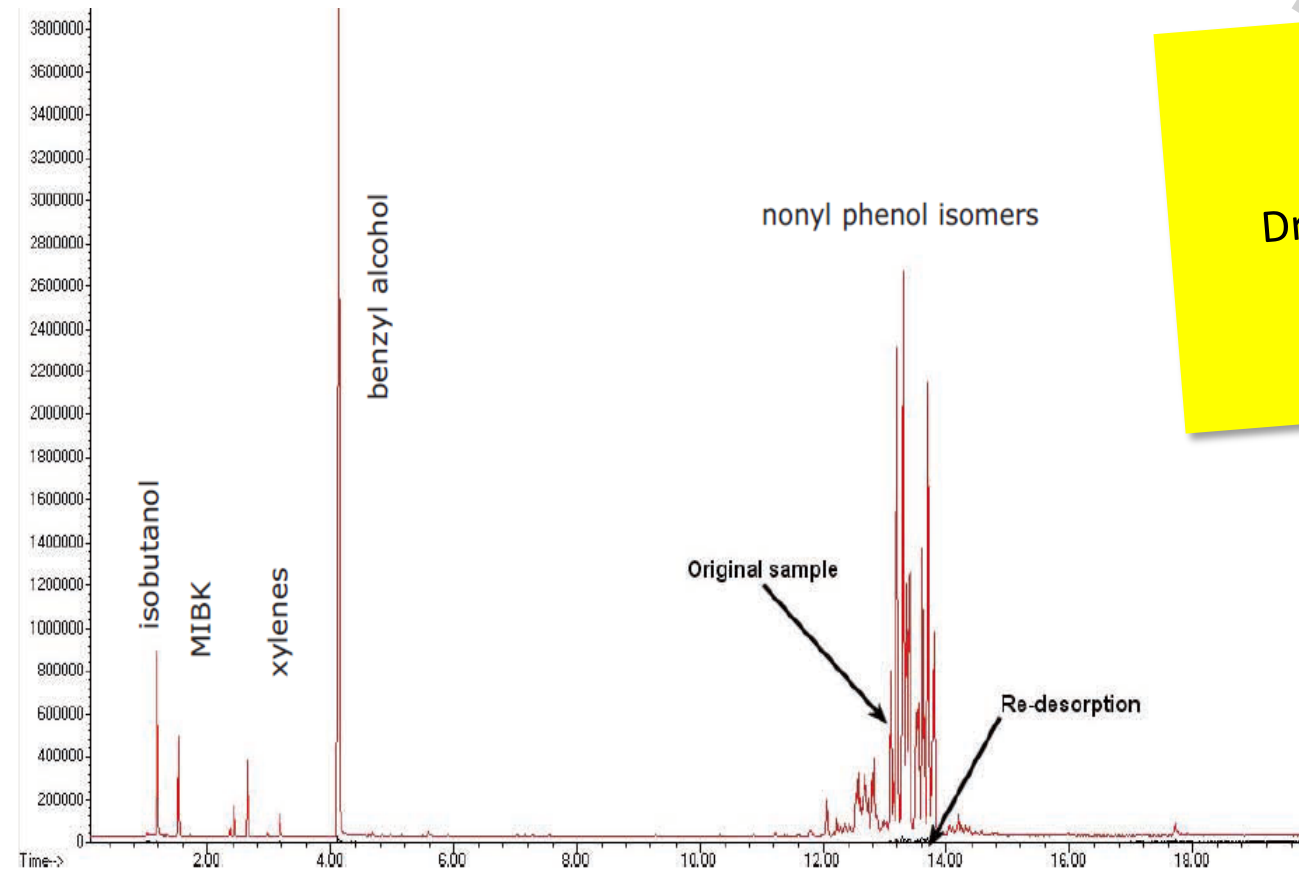


NON-ROUTINE MATERIAL EMISSION TESTING

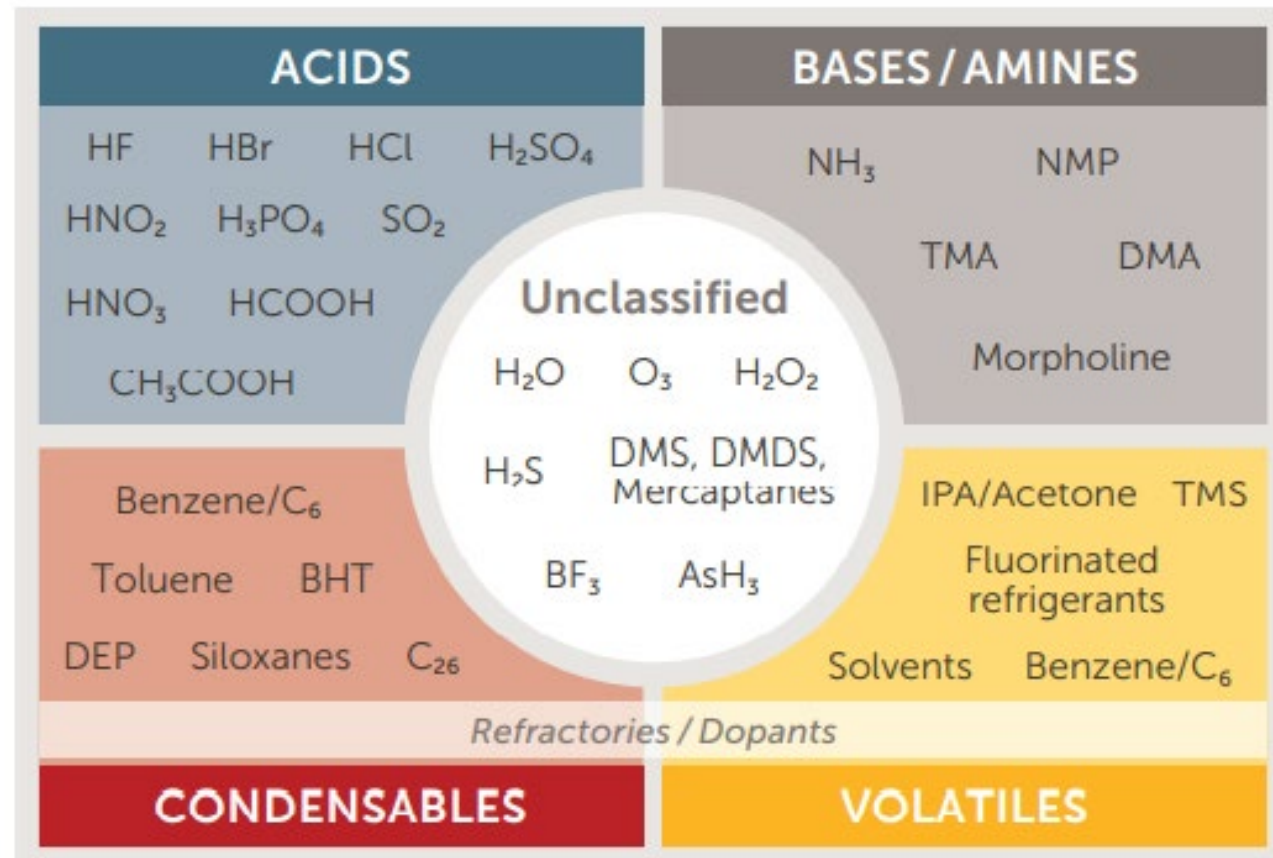


PVC foam sheet

NON-ROUTINE MATERIAL EMISSION TESTING



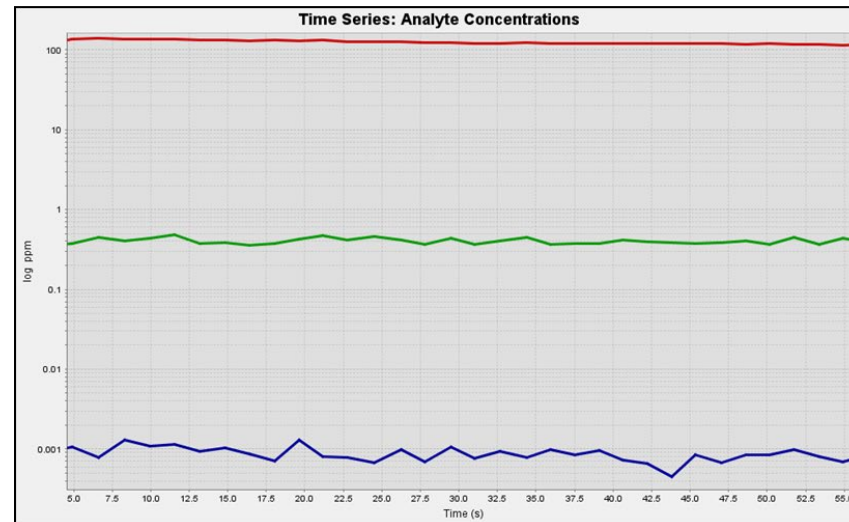
INNOVATION: SIFT-MS



INNOVATION: SIFT-MS



- Selected ion flow tube MS
- Direct analysis in real-time of:
 - volatile organic components
 - volatile inorganic components

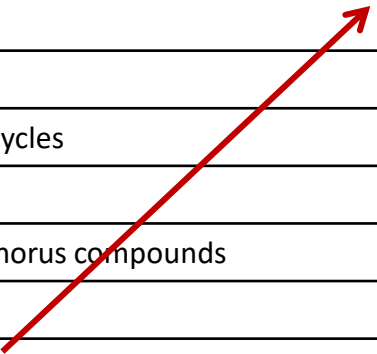


HCl [125 ppm]

Benzene [40 ppb]

Dimethyl sulfide [870 ppt]

TARGET COMPONENTS

Compound Class	Compound Class	Inorganics NH ₃ , PH ₃ , AsH ₃ , GeH ₃ B ₂ H ₆ , SiH ₄ , siloxanes, H ₂ S, HF, HCl, HBr, Cl ₂ , Br ₂ , SO ₂ , CO ₂ , N ₂ O
Alkanes	Nitrogen heterocycles	
Alkenes and dienes	Nitrated organics	
Alkynes and diyne	Oximes	
Aromatic hydrocarbons	Nitriles	
Terpines	Halogenated alkanes and alkenes	
Alcohols and diols	Halogenated aromatics	
Aldehydes and dialdehydes	Miscellaneous halogenated organics	
Ketones	Thiols	
Carboxylic acids	Thioalcohols	
Esters	Thioacids	
Ethers	Thioethers	
Cellosolves	Sulfur heterocycles	
Oxygen heterocycles	Sulfoxides	
Epoxides	Organophosphorus compounds	
Amines	Inorganics	
Amides		

APPLICATIONS

- TOC analysis
- Material emissions
- Online monitoring

Material emissions

- Similar strategy as TD
- Immediate response
- Ideal for fast troubleshooting
- Includes the emission of inorganics!



On-line monitoring

- Multipoint sampling
- High temporal resolution
- Organics + inorganics!



CONCLUDING REMARKS



More info?

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